

Crystal LTD TM SPEC Form

Customer

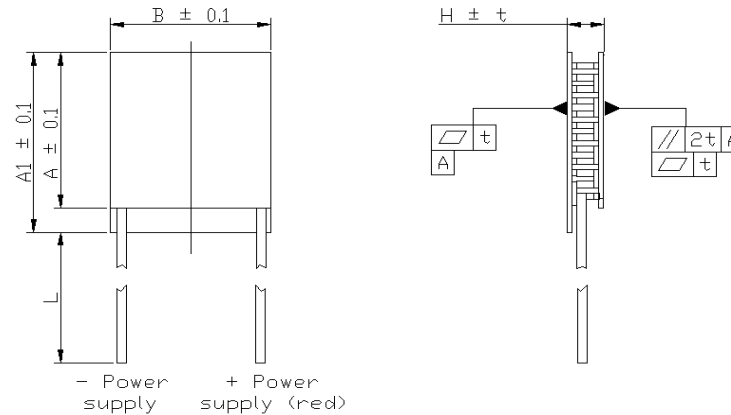
PO#

PO date

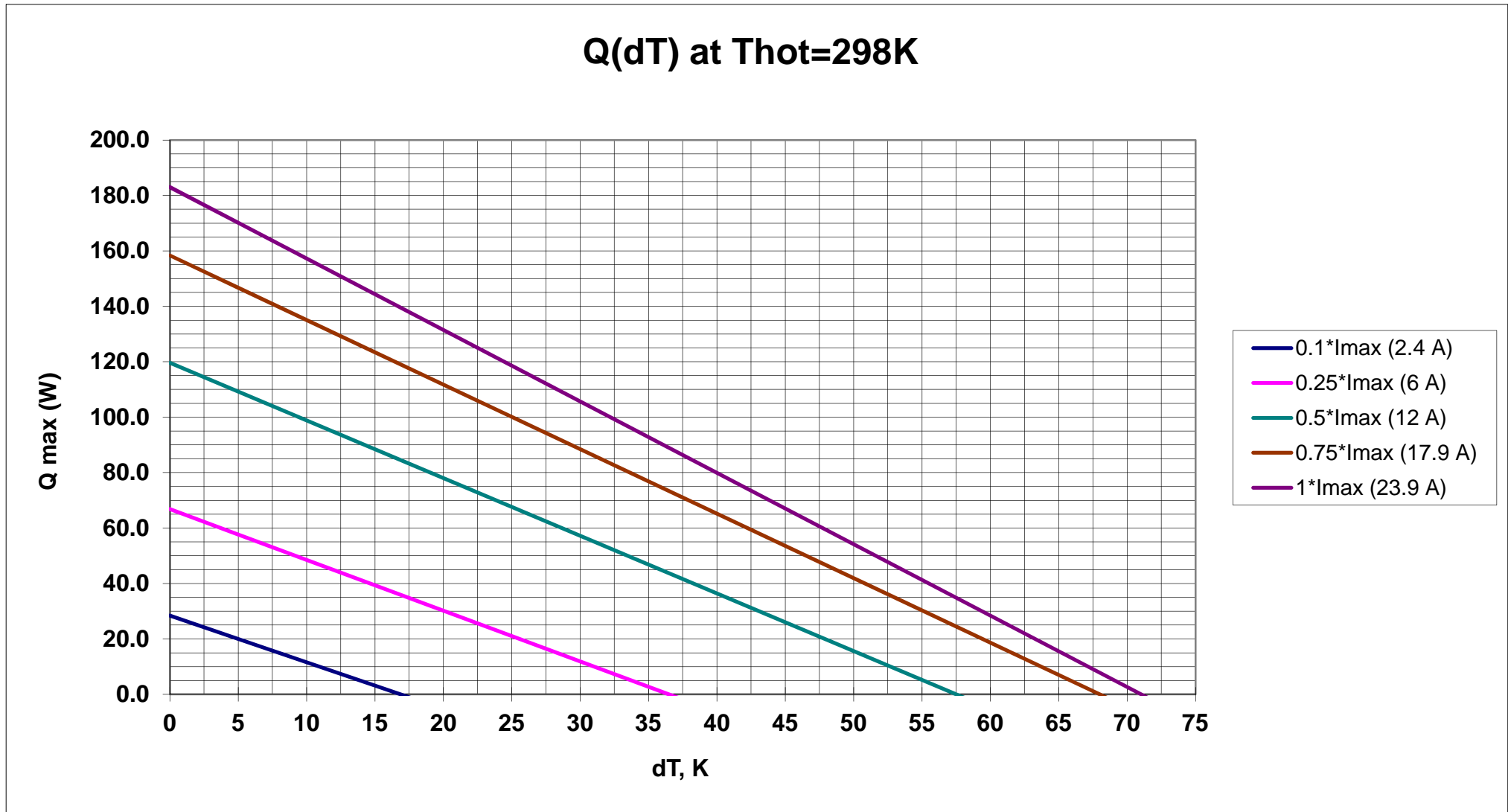
Thermoelectric module (TM) specification

PO position #	TM	Internal Solder Melting Temp, C	Max operating temperature, °C		Hot side temperature 25 °C				Rac at 25 °C		Ceramic size, mm		TM Height		Wire			Sealing
			short time	long time	I _{max} , A	U _{max} , V	Q _{max} , W	dT _{max} , K	Rac, Ohm	Tolerance ±, %	A/A1	B	Height, mm	Tolerance t, ± mm	S, AWG#	Length, mm	Tolerance ±, mm	
1	D-097-216-09-L2	138	130	115	23.9	12.4	183.0	71.0	0.39	10	49/49	49	3.80	0.02	18	100	5	
	ceramics: AlN														PVC			
	lamel version														soldered on external lamels (tabs)			

Clamping force: 54.6 - 109.2 kg



Max dT is reduced by 2-3K for silicon sealed and 1-2K for epoxy sealed versions.



U(dT) at $T_{hot}=298K$

